



Client Matter No. 81848.0016.001
Express Mail No.: EV330612835US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>Serial No. 09/546,174 Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun Filed: April 11, 2000 Art Unit: 1711 Examiner: Sergeant, Rabon A. Attorney Docket No. UMC-96-279 CON (JIA-462C1) For: HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS</p>	<p>Confirmation No.: 4793 Customer No.: 25235</p>
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AMENDMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the office communication mailed January 25, 2005,
please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which
begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.